Dear Colleague,

I invite you to submit a paper to the mini-symposium **"Numerical Methods in Fracture Mechanics",** organised by Technical Committee 8 "Numerical Methods" of the European Structural Integrity Society, within the framework of the 22nd European Conference on Fracture - ECF22, to be held in Belgrade, Serbia, 26-31 August 2018 **(http://www.ecf22.rs/). The deadline for the paper submission is 30th June 2018**.

The aim of this Symposium is to bring together specialists in numerical methods, keeping in mind spectacular progress over last few decades, or better to say, explosion from a small village of number of enthusiasts back in seventies, to a megacity of researchers producing beautiful colorful images of fracture mechanics problems, be it brittle, ductile, plastic, fatigue, creep... static, dynamic or impact... metallic or non-metallic.

The topics of the Symposium include, but are not limited to, the following:

- Linear Elastic Fracture Mechanics problems;
- Elastic Plastics problems, including cohesion problems and interfaces;
- Micromechanical modeling;
- Damage Mechanics: ductile, brittle, transition and including creep;
- Fatigue crack growth simulation (e.g. XFEM);
- Modeling of 3D cracks

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A selection of papers presented at this Symposium will be published in a Special Issue of **Engineering Fracture Mechanics, International Journal of Fatigue, Engineering Failure Analysis and/or Theoretical and Applied Fracture Mechanics, as well as Structural Integrity and Life.**

A special issue of Engineering Fracture Mechanics on "**Continuum damage models for ductile fracture**" is currently under preparation (deadline for submission is april 2019). The mini-symposium will also be a good opportunity to present work related to this topic.

IMPORTANT:
1) When submitting a paper please mention mini-symposium "Numerical Methods in Fracture Mechanics".
2) Please inform me about your submission (jacques.besson@mines-paristech.fr).
3) Please forward this invitation also to your colleagues interested in the subject.

With best regards,
Jacques Besson,
ESIS TC8 Chair